

PMP9108 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C2, C3, C4	4	2.2uF	GRM32ER72A225KA35L	MuRata	CAP, CERM, 2.2uF, 100V, +/-10%, X7R, 1210	1210
C5	1	0.047uF	GRM31CR72E473KW03L	MuRata	CAP, CERM, 0.047uF, 250V, +/-10%, X7R, 1206	1206
C7, C14, C20	3	0.1uF	STD	STD	CAP, CERM, 25V, +/-10%, X7R, 0402	0402
C8	1	DNP	N/A	N/A	Do Not Populate	RCAP, 6.3x8mm
C9, C10, C11, C12, C13	5	100uF	STD	STD	CAP, CERM, 10V, +/-20%, X5R, 1210	1210
C15	1	47pF	STD	STD	CAP, CERM, 50V, +/-10%, X7R, 0402	0402
C16	1	22uF	STD	STD	CAP, CERM, 25V, +/-10%, X7R, 1210	1210
C17	1	0.047uF	STD	STD	CAP, CERM, 25V, +/-10%, X7R, 0402	0402
C18	1	1000pF	STD	STD	CAP, CERM, 1000pF, 3kV, 1808	1808
C19	1	1000pF	STD	STD	CAP, CERM, 25V, +/-10%, X7R, 0402	0402
C21, C22	2	1uF	STD	STD	CAP, CERM, 16V, +/-10%, X5R, 0402	0402
C23	1	0.015uF	GRM155R71H153KA12D	MuRata	CAP, CERM, 0.015 uF, 50 V, +/- 10%, X7R, 0402	0402
C25	1	10uF	STD	STD	CAP, CERM, 16V, +/-10%, X5R, 1206	1206
D1	1	100V	MMSD4148T1G	ON Semiconductor	Diode, Switching, 100V, 0.2A, SOD-123	SOD-123
D2	1	5.1V	MMSZ4689-V	Vishay-Semiconductor	Diode, Zener, 5.1V, 500mW, SOD-123	SOD-123
D3, D4, D5, D6, D7	5	1.4V	BAS316,115	NXP Semiconductor	Diode, Ultrafast, 100V, 0.25A, SOD-323	SOD-323
L1	1	4.7uH	XAL8080-472ME	Coilcraft	Inductor, Shielded, Composite, 4.7uH, 10.5A, 8.89 ohm, SMD	8.1 x 8 x 8.6mm
L2	1	1mH	LPS4414-105MLB	Coilcraft	Inductor, Shielded Drum Core, Ferrite, 1mH, 0.11A, 16.3 ohm, SMD	LPS4414
Q1	1	0.7V	BC846BLT1G	ON Semiconductor	Transistor, NPN, 65V, 0.1A, SOT-23	SOT-23
Q2	1	30V	CSD17309Q3	Texas Instruments	MOSFET, N-CH, 30V, 60A, SON 3.3x3.3mm	SON 3.3x3.3mm
Q3	1	-30V	IRF6216TRPBF	International Rectifier	MOSFET P-CH 150V 2.2A 8-SOIC	SOIC-8
Q4	1	60V	CSD18540Q5B	Texas Instruments	MOSFET, N-CH, 60V, 28A, SON 5x6mm	SON 5x6mm
Q5	1	150V	FDMS86200	Fairchild Semiconductor	MOSFET, N-CH, 150V, 35A, PQFN08A	PQFN08A
Q6	1	0.25V	MMBT3906	Fairchild Semiconductor	Transistor, PNP, 40V, 0.2A, SOT-23	SOT-23
R1	1	511	STD	STD	RES, 1%, 0.125W, 0805	0805
R3	1	10	STD	STD	RES, 1%, 0.1W, 0603	0603
R4, R22, R24	3	10k	STD	STD	RES, 1%, 0.063W, 0402	0402
R5, R15, R17	3	0	STD	STD	RES, 1%, 0.063W, 0402	0402
R6, R20, R21	3	1k	STD	STD	RES, 1%, 0.063W, 0402	0402
R7	1	191k	STD	STD	RES, 1%, 0.063W, 0402	0402
R8	1	80.6k	STD	STD	RES, 1%, 0.063W, 0402	0402
R9	1	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R10, R16	2	100k	STD	STD	RES, 1%, 0.063W, 0402	0402
R11	1	0.1	STD	STD	RES, 1%, 1W, 2010	2010
R12, R13	2	3.01k	STD	STD	RES, 1%, 0.063W, 0402	0402
R14	1	90.9k	STD	STD	RES, 1%, 0.063W, 0402	0402
R18	1	301	CRCW0402301RFKED	Vishay-Dale	RES, 301, 1%, 0.063 W, 0402	0402
R19	1	402	CRCW0603402RFKEA	Vishay-Dale	RES, 402, 1%, 0.1 W, 0603	0603
R25	1	3.32k	CRCW04023K32FKED	Vishay-Dale	RES, 3.32 k, 1%, 0.063 W, 0402	0402
T1	1	153uH	PH0806.005NL	Pulse Engineering	Transformer, High Frequency Flat Coil Planar, SMT	920x910x850mil
TP1, TP2	2		8600-0-05-80-00-00-03-0	Mill-Max	PCB Pin, solderless Pressfit, Tin over Nickel	PCB Pin
TP3, TP4	2		8952-0-05-80-00-00-03-0	Mill-Max	PCB Pin, solderless Pressfit, Tin over Nickel	PCB Pin
U1	1		UCC27511DBV	Texas Instruments	Single-Channel High-Speed Low-Side Gate Driver (with 4-A Peak Source and 8-A Peak Sink), DBV0006A	DBV0006A

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U2	1		UCC2897ARGPR	Texas Instruments	Advanced Active Clamp PWM Controller with Current Control, -40 to +125 degC, 20-pin QFN (RGP), Green (RoHS & no Sb/Br)	RGP0020D
U3	1		VOL618A-2T	Vishay-Semiconductor	OPTOCOUPLR PHOTOTRANS 125% 4LSOP	8x2x4mm
U4	1		TLV431AIDBZ	Texas Instruments	LOW-VOLTAGE ADJUSTABLE PRECISION SHUNT REGULATOR, DBZ0003A	DBZ0003A

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